

Patent Abstracts of Japan

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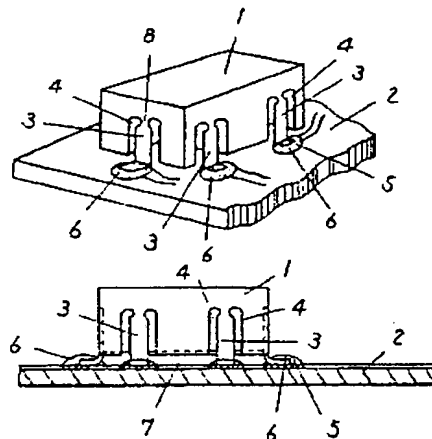
APPLICATION DATE : 18-09-87
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APPLICANT : MATSUSHITA ELECTRIC IND CO LTD;

INVENTOR : SAITO SUSUMU;

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TITLE : SHIELD-CASE ATTACHING DEVICE



ABSTRACT : PURPOSE: To prevent adverse effects on inner parts, by providing a pair of cut-out parts in a shield case, forming cut and raised pieces between both cut-out parts, setting the length of the piece so that a gap is formed between a board and the bottom surface of the case, and radiating heat in soldering.

CONSTITUTION: A plurality of cut and raised pieces 3 for soldering to a board 2 are provided in a shield case 1, which constitutes the outer package of a parts. Cut-out parts 4 are provided at the right and left neighboring parts of the cut and raised pieces 3. A narrow part 8 is provided at a part of each cut and raised piece 3. Thus, heat, which is conducted from the board 2 when the board 2 undergoes flow dipping, is conducted to parts through the cut and raised pieces 3. Large heat resistance is provided at the cross section of each cut and raised piece 3. The temperature increase of the main body of the case is largely suppressed. Therefore, heat dissipation becomes large as the main body of the case is approached. Thermal damage to the main body of the case is decreased. Even if solder is used for the junction part of the case and the content, no trouble is yielded at all.

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